

**Electronic Assembly With Sandwiched Capacitors
And Methods of Manufacture**

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Abstract of the Disclosure

10 To provide high-speed, low inductance capacitive decoupling, an integrated
circuit (IC) package includes capacitors positioned within the mounting region
between a die and an IC package substrate. A variety of types and sizes of
capacitors and substrates can be employed in a variety of geometrical arrangements.
In some embodiments, capacitors are sandwiched between die terminals or bumps
and the substrate conductors or pads, while in other embodiments, capacitors are
15 positioned between bar-type conductors on the surface of the IC package substrate.
Methods of fabrication, as well as application of the package to an electronic
assembly and to an electronic system, are also described.

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